



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





DS34S132

32-Port TDM-over-Packet IC

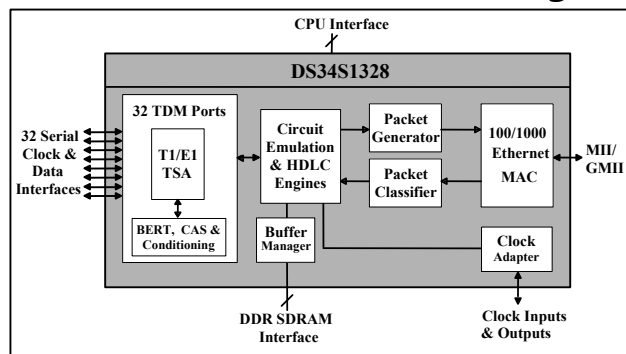
General Description

The IETF PWE3 SAToP/CESoPSN/HDLC-compliant DS34S132 provides the interworking functions that are required for translating TDM data streams into and out of TDM-over-Packet (TDMoP) data streams for L2TPv3/IP, UDP/IP, MPLS (MFA-8), and Metro Ethernet (MEF-8) networks while meeting the jitter and wander timing performance that is required by the public network (ITU G.823, G.824, and G.8261). Up to 32 TDM ports can be translated into as many as 256 individually configurable pseudowires (PWs) for transmission over a 100/1000Mbps Ethernet port. Each TDM port's bit rate can vary from 64Kbps to 2.048Mbps to support T1/E1 or slower TDM rates. PW interworking for TDM-based serial HDLC data is also supported. A built-in time-slot assignment (TSA) circuit provides the ability to combine any group of time slots (TS) from a single TDM port into a single PW. The high level of integration provides the perfect solution for high-density applications to minimize cost, board space, and time to market.

Applications

TDM Circuit Emulation Over PSN
 TDM Leased-Line Services Over PSN
 TDM Over BPON/GPON/EPON
 TDM Over Cable
 TDM Over Wireless
 Cellular Backhaul
 Multiservice Over Unified PSN
 HDLC-Encapsulated Data Over PSN

Functional Diagram



Features

- ◆ 32 Independent TDM Ports with Serial Data, Clock, and Sync (Data = 64Kbps to 2.048Mbps)
- ◆ One 100/1000Mbps (MII/GMII) Ethernet MAC
- ◆ 256 Total PWs, 32 PW per TDM Port, with Any Combination of TDMoP and/or HDLC PWs
- ◆ PSN Protocols: L2TPv3 or UDP Over IP (IPv4 or IPv6), Metro Ethernet (MEF-8), or MPLS (MFA-8)
- ◆ 0, 1, or 2 VLAN Tags (IEEE 802.1Q)
- ◆ Synchronous or Asynchronous TDM Port Timing
 - One Clock Recovery Engine per TDM Port with One Assignable as a Global Reference
 - Supported Clock Recovery Techniques
 - Adaptive Clock Recovery
 - Differential Clock Recovery
 - Absolute and Differential Timestamps
 - Independent Receive and Transmit Interfaces
 - Two Clock Inputs for Direct Transmit Timing
- ◆ For Structured T1/E1, Each TDM Port Includes DS0 TSA Block for any Time Slot to Any PW
- ◆ 32 HDLC/CES Engines (256 Total) With or Without CAS Signaling
- ◆ For Unstructured, each TDM Port Includes One HDLC/SAT Engine (32 Total)
- ◆ Any data rate from 64Kbps to 2.048Mbps
- ◆ 32-Bit or 16-Bit CPU Processor Bus
- ◆ CPU-Based OAM and Signaling
 - UDP-specific "Special" Ethernet Type
 - Inband VCCV ARP
 - MEF OAM NDP/IPv6
 - Broadcast DA
- ◆ DDR SDRAM Interface
- ◆ Low-Power 1.8V Core, 3.3V I/O, 2.5V SDRAM

Ordering Information

PART	PORTS	TEMP RANGE	PIN-PACKAGE
DS34S132GNA2	32	-40°C to +85°C	676 BGA
DS34S132GNA2+	32	-40°C to +85°C	676 BGA

+Denotes a lead(Pb)-free/RoHS-compliant package.



TABLE OF CONTENTS

1	Introduction.....	8
2	Acronyms and Glossary	9
3	Applicable Standards	10
4	High Level Description	11
5	Application Examples.....	13
6	Block Diagram	15
7	Features	16
8	Pin Descriptions.....	20
8.1	Short Pin Descriptions	20
8.2	Detailed Pin Descriptions.....	22
9	Functional Description.....	27
9.1	Connection Types.....	29
9.1.1	SAT/CES Payload Connections	29
9.1.2	HDLC Connections	29
9.1.3	SAT/CES PW-Timing Connections.....	30
9.1.4	CPU Connections	31
9.2	TDM Port Functions.....	32
9.2.1	TDM Port Related Input and Output Clocks.....	32
9.2.1.1	PW-Timing.....	33
9.2.1.1.1	RXP Clock Recovery (RXP PW-Timing)	34
9.2.1.1.2	TXP PW-Timing	34
9.2.1.2	TDM Port - One Clock and Two Clock Modes.....	35
9.2.2	TDM Port Interface.....	35
9.2.2.1	TDM Port Transmit Interface	36
9.2.2.2	TDM Port Receive Interface	37
9.2.3	TDM Port Structure & Frame Formats.....	37
9.2.4	Timeslot Assignment Block	38
9.2.4.1	TDM CAS to Packet CAS Translation.....	40
9.2.4.2	TSA Block Loopbacks	42
9.2.5	TDM Port Data Processing Engines	42
9.2.5.1	HDLC Engine.....	43
9.2.5.1.1	SAT/CES Engine.....	44
9.2.5.2	TDM Port Priority.....	45
9.2.5.3	Jitter Buffer Settings.....	45
9.2.6	TDM Diagnostic Functions	50
9.2.6.1	TDM Loopback.....	50
9.2.6.2	TDM BERT	51
9.3	Packet Processing Functions.....	53
9.3.1	Ethernet MAC	53
9.3.1.1	Ethernet Port Diagnostic Functions	54
9.3.1.1.1	Ethernet Loopback	54
9.3.1.1.2	Packet BERT	54
9.3.2	RXP Packet Classification.....	56
9.3.2.1	Generalized Packet Classification	56
9.3.2.2	PW (BID and OAM BID) Packet Classification	57
9.3.2.2.1	UDP Settings	58
9.3.2.2.2	Handling of Packets with a Matching BID or OAM BID.....	58
9.3.2.2.3	L-bit Signaling for RXP PWs.....	59
9.3.2.3	CPU Packet Classification.....	59
9.3.2.3.1	Packets with Broadcast Ethernet DA (DPC.CR1.DPBTP and DPC.CR1.DPBCP)	60
9.3.2.3.2	Packets with Unknown Ethernet DA (PC.CR7 – PC.CR19 and DPC.CR1.DPS9).....	60
9.3.2.3.3	PW Packets with Unknown PW-ID (DPS6)	60
9.3.2.3.4	MEF OAM Ethernet Type Packets (MOET).....	60
9.3.2.3.5	CPU Destination Ethernet Type Packets (CDET and DPS8).....	60
9.3.2.3.6	ARP Packet with Known IP Destination Address (PC.CR6 – PC.CR8 and DPS3).....	60
9.3.2.3.7	ARP Packet with Unknown IP Destination Address (PC.CR6 – PC.CR8 and DPS0)	60
9.3.2.3.8	Packet with Unknown Ethernet Type (DPS2).....	60

9.3.2.3.9	IP Packets with Unknown IP Protocol (DPS4).....	60
9.3.2.3.10	IP Packet with Unknown IP Destination Address (PC.CR6 – PC.CR16 and DPS1)	60
9.3.2.3.11	“CPU Debug RXP PW Bundle” Setting (RXBDS).....	61
9.3.2.3.12	PW Bundle with Unknown UDP Protocol Type (UPVCE and DPS5).....	61
9.3.2.3.13	PW Bundle In-band VCCV OAM (RXOICWE and DPS7).....	61
9.3.2.3.14	PW Bundle with Too Many MPLS Labels (DPS10).....	61
9.3.2.3.15	PW OAM Bundle - Out-band VCCV OAM Packets (DPS7)	61
9.3.3	TXP Packet Generation	61
9.3.3.1	TXP SAT/CES/HDLC/Clock Only PW Packet Generation	62
9.3.3.1.1	L-bit Signaling	63
9.3.3.2	TXP CPU Packet Generation	63
9.3.3.3	TXP Packet Scheduling.....	63
9.3.3.4	TXP Packet Queue Monitoring	63
9.4	CPU Packet Interface	63
9.4.1	RXP CPU Packet Interface	63
9.4.2	TXP CPU Packet Interface.....	66
9.5	Clock Recovery Functions	68
9.6	Miscellaneous Global Functions.....	68
9.6.1	Global Resets	68
9.6.2	Latched Status and Counter Register Reset.....	68
9.6.3	Buffer Manager	68
9.6.3.1	SDRAM Interface	69
9.6.4	CPU Electrical Interconnect	69
9.6.5	Interrupt Hierarchy	71
10	Device Registers.....	74
10.1	Register Block Address Ranges.....	74
10.2	Register Address Reference List.....	75
10.3	Register Definitions.....	83
10.3.1	Global Registers (G.).....	83
10.3.1.1	Global Configuration Registers (G.).....	83
10.3.1.2	Global Status Registers (G.).....	86
10.3.1.3	Global Status Register Interrupt Enables (G.).....	88
10.3.2	Bundle Registers (B.).....	89
10.3.2.1	Bundle Reset Registers (B.).....	89
10.3.2.2	Bundle Data Control Registers (B.).....	90
10.3.2.3	Bundle Data Registers (B.).....	91
10.3.2.4	Bundle Status Latch Registers (B.).....	97
10.3.2.5	Bundle Status Register Interrupt Enables (B.).....	100
10.3.3	Jitter Buffer Registers (JB.).....	104
10.3.3.1	Jitter Buffer Status Registers (JB.).....	104
10.3.3.2	Jitter Buffer Status Register Interrupt Enables (JB.).....	107
10.3.4	Packet Classifier Registers (PC.)	110
10.3.4.1	Packet Classifier Configuration Registers (PC.).....	110
10.3.4.2	Packet Classifier Status Register Latches (PC.)	113
10.3.4.3	Packet Classifier Status Register Interrupt Enables (PC.).....	114
10.3.4.4	Packet Classifier Counter Registers (PC.)	115
10.3.5	External Memory Interface Registers (EMI.).....	115
10.3.5.1	External Memory Interface Configuration Registers (EMI.).....	115
10.3.5.2	External Memory Interface Status Registers (EMI.).....	116
10.3.5.3	External Memory Interface Status Register Interrupt Enables (EMI.).....	117
10.3.5.4	External Memory DLL/PLL Test Registers (EMI.).....	118
10.3.6	External Memory Access Registers (EMA.).....	118
10.3.6.1	Write Registers (EMA.).....	118
10.3.6.2	Read Registers (EMA.)	120
10.3.7	Encap BERT Registers (EB.)	122
10.3.8	Decap BERT Registers (DB.).....	124
10.3.9	Miscellaneous Diagnostic Registers (MD.)	126
10.3.10	Test Registers (TST.).....	127
10.3.11	Clock Recovery Registers (CR.).....	129

10.3.12	MAC Registers (M.)	129
10.3.13	TXP SW CAS Registers (TXSCn.)	138
10.3.14	Xmt (RXP) SW CAS Registers (RXSCn.)	139
10.3.15	TDM Port n Registers (Pn.; n = 0 to 31)	140
10.3.15.1	Port n Transmit Configuration Registers (Pn.)	140
10.3.15.2	Port n Transmit Status Registers (Pn.)	142
10.3.15.3	Port n Transmit Status Register Latches (Pn.)	143
10.3.15.4	Port n Transmit Status Register Interrupt Enables (Pn.)	143
10.3.15.5	Port n Receive Configuration Registers (Pn.)	144
10.3.15.6	Port n Receive Status Registers (Pn.)	146
10.3.15.7	Port n Receive Status Register Latches (Pn.)	147
10.3.15.8	Port n Receive Status Register Interrupt Enables (Pn.)	147
10.3.16	Timeslot Assignment Registers (TSAn.m.; “n” = TDM Port n; “m” = Timeslot m)	147
10.4	Register Guide	148
10.4.1	Global Packet Settings	149
10.4.2	Bundle and OAM Bundle Settings	151
10.4.2.1	SAT Bundle Settings	152
10.4.2.2	CES without CAS Bundle Settings	153
10.4.2.3	CES with CAS Bundle Settings	154
10.4.2.4	Unstructured HDLC Bundle (any Line Rate) Settings	155
10.4.2.5	Structured Nx64 Kb/s HDLC Bundle Settings	156
10.4.2.6	Structured 16 Kb/s or 56 Kb/s HDLC Bundle Settings	157
10.4.2.7	Clock Only Bundle Settings	158
10.4.2.7.1	Combined RXP and TXP (Bidirectional) Clock Only Bundle Settings	158
10.4.2.7.2	RXP (Unidirectional) Clock Only Bundle Settings	159
10.4.2.7.3	TXP (Unidirectional) Clock Only Bundle Settings	160
10.4.2.8	“CPU RXP PW Debug” Bundle Settings	161
10.4.2.9	In-band VCCV OAM Connection Settings	162
10.4.2.10	OAM Bundle (Out-band VCCV OAM) Settings	162
10.4.3	Send to CPU Settings	163
10.4.4	TDM Port Settings	163
10.4.5	Status Monitoring	167
10.4.5.1	Ethernet Port Monitoring	167
10.4.5.2	Global Packet Classifier Monitoring Control	168
10.4.5.3	Global RXP Bundle Monitoring Control	168
10.4.5.4	Global TXP Packet Queue Monitoring	168
10.4.5.5	PW Bundle Monitoring	168
10.4.6	SDRAM Settings	169
11	JTAG Information	171
12	DC Electrical Characteristics	172
13	AC Timing Characteristics	173
13.1	CPU Interface	173
13.2	TDM Interface	175
13.3	MAC Interface	177
13.3.1	GMII Interface	177
13.3.2	MII Interface	177
13.4	DDR SDRAM Timing	178
14	Pin Assignment	180
15	Package Information	192
16	Thermal Information	193
17	Data sheet Revision History	194

LIST OF FIGURES

Figure 5-1. TDMoP in a Metropolitan Packet Switched Network	13
Figure 5-2. TDMoP in Cellular Backhaul.....	14
Figure 6-1. DS34S132 Functional Block Diagram.....	15
Figure 9-1. S132 Block Diagram	28
Figure 9-2. RXP/TXP Data Path Directions	28
Figure 9-3. SAT/CES Payload Connection	29
Figure 9-4. Bundle HDLC Connection	29
Figure 9-5. Bundle PW-Timing Connections.....	30
Figure 9-6. CPU Connections	31
Figure 9-7. TDM Port Input and Output Clock Overview	32
Figure 9-8. Clock Recovery Engine Environment.....	34
Figure 9-9. TXP PW-Timing Environment.....	34
Figure 9-10. TDM Port #1 Environment.....	35
Figure 9-11. Logic Detail for a Single TDM Port Interface	36
Figure 9-12. T1 ESF CAS to SF CAS Translation Example	37
Figure 9-13. TSA Block Environment	39
Figure 9-14. HDLC Engine Environment	43
Figure 9-15. SAT/CES Engine Environment.....	44
Figure 9-16. Bundle Jitter Buffer FIFO.....	48
Figure 9-17. T1/E1 Port Line Loopback and TDM Port Timeslot Loopback Diagram	51
Figure 9-18. T1/E1 Port Bundle Loopback Diagram.....	51
Figure 9-19. TDM Port BERT Diagram.....	51
Figure 9-20. Ethernet MAC Environment.....	53
Figure 9-21. Ethernet Port Local Loopback	54
Figure 9-22. Ethernet Port BERT Diagram	55
Figure 9-23. RXP Packet Classifier Environment.....	56
Figure 9-24. TXP Packet Generation Environment	61
Figure 9-25. SAT/CES/HDLC/Clock Only PW TXP Header Descriptor.....	62
Figure 9-26. Stored RXP CPU Packet.....	64
Figure 9-27. Stored TXP CPU Packet and Header Descriptor	66
Figure 9-28. Buffer Manager Environment.....	68
Figure 9-29. MPC870 32-bit Bus Interface.....	70
Figure 9-30. MPC8313, Non-multiplexed Bus Interface	71
Figure 9-31. MPC8313, Multiplexed Bus Interface.....	71
Figure 9-32. Interrupt Hierarchy Diagram	73
Figure 10-1. Register Guide High Level Diagram.....	148
Figure 13-1. MPC870-like processor CPU Interface Write Cycle.....	174
Figure 13-2. MPC870-like processor CPU Interface Read Cycle	174
Figure 13-3. MPC8313-like processor CPU Interface Write Cycle.....	174
Figure 13-4. MPC8313-like processor CPU Interface Read Cycle	175
Figure 13-5. TDM Port using Single Clock (TCLKO), positive edge timing (RSS = 1, TIES = RIES = 0)	176
Figure 13-6. TDM Port using Two Clock, negative edge timing (RSS = 0, TIES = RIES = 1).....	176
Figure 13-7. GMII Transmit Timing.....	177
Figure 13-8. GMII Receive Timing.....	177
Figure 13-9. MII Transmit Timing	178
Figure 13-10. MII Receive Timing.....	178
Figure 13-11. DDR SDRAM Timing.....	179
Figure 15-1. 676-Ball TEPBGA (56-G6029-001).....	192

LIST OF TABLES

Table 3-1. Applicable Standards	10
Table 8-2. Detailed Pin Descriptions	22
Table 9-2. TDM Port TCLKOn Clock Source Selection	36
Table 9-3. TDM Port BFD Settings.....	38
Table 9-4. CAS Translation using RSIG and TSIG	41
Table 9-5. CAS Translation using RDAT and TDAT	42
Table 9-6. PDV Parameters that affect the latency of a PW packet.....	46
Table 9-7. Maximum S132 Ethernet Media PDV	47
Table 9-8. Recognized PW Ethernet Types.....	57
Table 9-9. Malformed PW Header Handling (not including the UDP specific settings).....	59
Table 9-10. Bundle Forwarding Options	59
Table 9-11. TXP SAT/CES/HDLC/Clock Only PW Header Control	62
Table 9-12. RXP CPU Header Descriptor – 1 st Dword	64
Table 9-13. RXP CPU Header Descriptor – 2 nd Dword	65
Table 9-14. RXP CPU Header Descriptor – 3 rd Dword	65
Table 9-15. TXP CPU Header Control.....	66
Table 9-16. Modify FCS and Add TXP OAM Timestamp Functions.....	67
Table 9-17. SDRAM Device Selection Table	69
Table 9-18. Interrupt Hierarchy.....	72
Table 10-1. Register Block Address Ranges	74
Table 10-3. Global Configuration Registers	83
Table 10-4. Global Status Registers (G.).....	86
Table 10-5. Global Status Register Interrupt Enables (G.)	88
Table 10-6. Bundle Reset Registers (G.).....	89
Table 10-7. Bundle Data Control Registers (B.).....	90
Table 10-8. Bundle Data Registers (B.).....	91
Table 10-9. Bundle Status Latch Registers (B.).....	97
Table 10-10. Bundle Status Register Interrupt Enables (B.).....	100
Table 10-11. Jitter Buffer Status Registers (JB.).....	104
Table 10-12. Jitter Buffer Status Register Interrupt Enables (JB.)	107
Table 10-13. Packet Classifier Configuration Registers (PC.)	110
Table 10-14. Packet Classifier Register Latches (PC.)	113
Table 10-15. Packet Classifier Status Register Interrupt Enables (PC.)	114
Table 10-16. Packet Classifier Counter Registers (PC.)	115
Table 10-17. External Memory Interface Configuration Registers (EMI.).....	115
Table 10-18. External Memory Interface Status Registers (EMI.).....	116
Table 10-19. External Memory Interface Status Register Interrupt Enables (EMI.).....	117
Table 10-20. External Memory DLL/PLL Test Registers (EMI.).....	118
Table 10-21. Write Registers (EMA.).....	118
Table 10-22. Read Registers (EMA.).....	120
Table 10-23. Encap BERT Registers (EB.).....	122
Table 10-24. Decap BERT Registers (DB.)	124
Table 10-25. Miscellaneous Diagnostic Registers (MD.).....	126
Table 10-26. Test Registers (TST.).....	127
Table 10-27. MAC Registers (M.).....	129
Table 10-28. TXP SW CAS Registers (TXSCn.).....	138
Table 10-29. Xmt (RXP) SW CAS Registers (RXSCn.).....	139
Table 10-30. Port n Transmit Configuration Registers (Pn.).....	140
Table 10-31. Port n Transmit Status Registers (Pn.).....	142
Table 10-32. Port n Transmit Status Register Latches (Pn.)	143
Table 10-33. Port n Transmit Status Register Interrupt Enables (Pn.).....	143
Table 10-34. Port n Receive Configuration Registers (Pn.).....	144
Table 10-35. Port n Receive Status Registers (Pn.).....	146
Table 10-36. Port n Receive Status Register Latches (Pn.)	147
Table 10-37. Port n Receive Status Register Interrupt Enables (Pn.).....	147
Table 10-38. Timeslot Assignment Registers (TSAn.m.; “n” = TDM Port n; “m” = Timeslot m).....	147
Table 10-39. Global Ethernet MAC (M.) Control Register Settings (Values are in hex).....	149

Table 10-40. Global Ethernet Packet Classification (PC.) Settings.....	150
Table 10-41. Valid UDP BID Location and UDP Protocol Type Settings.....	151
Table 10-42. Bundle and OAM Bundle Control Registers (B.).....	151
Table 10-43. SAT Bundle Settings	152
Table 10-44. PMS/PDVT/MJBS for SAT with various PCT, PDV and BFD values.....	152
Table 10-45. CES without CAS Bundle Settings.....	153
Table 10-46. PMS/PDVT/MJBS for T1/E1 CES without CAS for various PCT, PDV and BFD values	153
Table 10-47. CES with CAS Bundle Settings.....	154
Table 10-48. PMS/PDVT/MJBS for T1/E1 CES with CAS for various PCT, PDV and BFD values	154
Table 10-49. Unstructured HDLC Bundle (any Line Rate) Settings	155
Table 10-50. Structured Nx64 Kb/s HDLC Bundle Settings.....	156
Table 10-51. Structured 16 Kb/s or 56 Kb/s HDLC Bundle Settings.....	157
Table 10-52. Combined RXP and TXP (Bidirectional) Clock Only Bundle Settings.....	158
Table 10-53. RXP (Unidirectional) Clock Only Bundle Settings.....	159
Table 10-54. TXP (Unidirectional) Clock Only Bundle Settings	160
Table 10-55. "CPU RXP PW Debug" Bundle Settings.....	161
Table 10-56. In-band VCCV OAM Connection Settings.....	162
Table 10-57. OAM Bundle PWID and Activation Control Registers (B.).....	162
Table 10-58. "Send to CPU" Quick Reference Settings	163
Table 10-59. Global TDM Port Settings.....	163
Table 10-60. TDM Port "n" Register Settings for T1 Applications (Pn.; n = 0 to 31)	164
Table 10-61. TDM Port "n" Register Settings for E1 Applications (Pn.; n = 0 to 31).....	165
Table 10-62. TDM Port "n" Register Settings for non-T1/E1 Applications (Pn.; n = 0 to 31).....	166
Table 10-63. Ethernet MAC Status Registers (M.).....	167
Table 10-64. Ethernet RMON Count Registers (M.; all are Read Only).....	167
Table 10-65. Global Packet Classifier Monitoring Settings (PC.).....	168
Table 10-66. Global RXP Bundle Control Word Change Monitor Settings(G.).....	168
Table 10-67. Global TXP Output Queue Status Registers (G.)	168
Table 10-68. TXP Bundle Status/Statistics Registers.....	168
Table 10-69. RXP Bundle Status/Statistics Registers ³	169
Table 10-70. SDRAM Settings (EMI.).....	169
Table 10-71. SDRAM Starting Address Assignments (EMI.; all SDRAM sizes)	169
Table 10-72. Example Max PDV (ms) for various PCT, JBMD and # of TS Combinations.....	169
Table 11-1. JTAG ID Code.....	171
Table 12-1. Recommended DC Operating Conditions ($T_j = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$.).....	172
Table 12-2. DC Electrical Characteristics ($T_j = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$.).....	173
Table 13-1. CPU Interface Timing ($V_{DD} = 3.3\text{V} \pm 5\%$, $T_j = -40^{\circ}\text{C}$ to 125°C .)	173
Table 13-2. TDM Ports.....	175
Table 13-3. GMII Transmit Timing.....	177
Table 13-4. GMII Receive Timing.....	177
Table 13-5. MII Transmit Timing.....	177
Table 13-6. MII Receive Timing.....	178
Table 13-7. DDR SDRAM Interface Timing	178
Table 14-1. Pins Sorted by Signal Name.....	180
Table 14-2. Pins Sorted by Ball Grid Array - Ball Number.....	184
Table 14-3. Pin Assignments according to Device Outline	188
Table 16-1. Thermal Package Information.....	193

1 INTRODUCTION

The public network is in transition from a TDM Switched Network to a Packet Switched Network. A number of Pseudowire (PW) packet protocols have been standardized to enable legacy TDM services (e.g. TDM voice, TDM Leased-line and HDLC encapsulated data) to be transported and switched/routed over a single, unified PSN. The legacy service is encapsulated into a PW protocol and then transported or tunneled through the unified PSN. The PW protocols provide the addressing mechanisms that enable a PSN to switch/route the service without understanding or directly regarding the specific characteristics of the services (e.g. the PSN does not have to directly understand the timing requirements of a TDM voice service). The PW protocols have been developed for use over PSNs that utilize the L2TPv3/IP, UDP/IP, MPLS (MFA-8) or Metro Ethernet (MEF-8) protocols.

PW protocols that are used for TDM services can be categorized as TDM-over-Packet (TDMoP) PW protocols. The TDMoP protocols support all of the aspects of the TDM services (data, timing, signaling and OAM). This enables Public (WAN) and Enterprise (LAN) networks to migrate to next generation PSNs and continue supporting legacy voice and leased-line services without replacing the legacy termination equipment.

Legacy TDM services depend on constant bit rate data streams with highly accurate frequency, jitter and wander timing requirements that up until recently have not been well supported by most packet switching equipment. For public network applications the timing recovery mechanisms must achieve the jitter and wander performance that is required by the ITU-T G.823/824/8261 standards. To accomplish this, a TDMoP terminating device must incorporate innovative and complex mechanisms to recover the TDM timing from a stream of packets.

Legacy TDM services also have numerous special features that include voice signaling and OAM systems that have been developed over many years through a long list of standardization literature to provide carrier-grade reliability and maintainability. The list of legacy functions and features is so long that today's VoIP equipment only supports a subset of what is used in the legacy TDM network. This, in part, has slowed the transition from a TDM to Packet-based network. With TDMoP technology all features and services can be supported.

The TDMoP technology is similar to VoIP technology in that both provide a means of communicating a time oriented service (e.g. voice) over a non-time oriented, packet network. TDMoP technology can be added incrementally to the network (as needed) to supplement VoIP technology to provide an alternative solution when VoIP price/performance is not optimal (e.g. where the number of supported lines does not warrant the infrastructure required of a VoIP network) and where some function/features are not supported by the VoIP protocols.

The Legacy PSTN network also supports HDLC encapsulated data that is transported over TDM lines. PWs can also be used to transport HDLC data. This form of PW could also be categorized as a TDM service since the legacy service is carried over TDM lines. However, the fundamental aspects of an HDLC service do not depend as much on TDM timing and the nature of the data can be described as "packetized" as with Ethernet, Frame Relay and ATM services. For clarity the HDLC service is categorized as "HDLC over PW". One example Legacy HDLC service is SS7 Signaling which is used to communicate voice signaling information from one TDM switch to another.

2 ACRONYMS AND GLOSSARY

- # – Number
- ACR – Adaptive Clock Recovery
- AT – Absolute Timestamps
- ATM – Asynchronous Transfer Mode
- BERT – Bit Error Rate Test
- BGA – Ball Grid Array
- BITS - Building Integrated Timing System
- Bundle – a PW with an ID that is recognized by the DS34S132
- BW – Bandwidth
- CR – Clock Recovery
- CAS – Channel Associated Signaling
- CCS – Common Channel Signaling
- CES – abbreviation for CESoPSN
- CESoPSN – Circuit Emulation Service over PSN
- CLAD – Clock Rate Adapter
- CRE – Clock Recovery Engine
- DA – Destination Address
- DCR – Differential Clock Recovery
- DCR-DT – DCR with Differential Timestamps
- DDR – Double Data Rate
- Decap –De-encapsulate
- DS0 – 64 Kb/s Timeslot within a T1 or E1 signal
- DS1 – 1.544 Mb/s TDM data stream
- E1 – 2.048 Mb/s TDM data stream
- Encap –Encapsulate
- EPON – Ethernet PON (IEEE 802.3ah)
- FCS – Frame Check Sequence
- GMII – Gigabit MII (IEEE 802.3)
- GPON – Gigabit PON (ITU-T G.984)
- GPS - Global Positioning System
- HDLC – High-level Data Link Control
- IEEE – Institute of Electrical & Electronic Engineers
- IETF – Internet Engineering Task Force
- IP – Internet Protocol
- ISDN – Integrated Services Digital Network
- ITU – International Telecommunication Union
- JB – Jitter Buffer
- L2TPv3 – Layer 2 Tunneling Protocol Version 3
- LAN – Local Area Network
- MAC – Media Access Control
- MAN – Metropolitan Area Network
- MEF – Metro Ethernet Forum
- MFA – MPLS/Frame Relay Alliance (Now called IP/MPLS Forum)
- MII – Medium Independent Interface (IEEE 802.3)
- MPLS – Multi-Protocol Label Switching
- OAM – Operations, Administration & Maintenance
- OCXO – Oven Controlled Crystal Oscillator
- OLT – Optical Line Termination
- ONU – Optical Network Unit
- PBX – Private Branch Exchange
- PDV – Packet Delay Variation
- PDVT – PDV Tolerance
- PON – Passive Optical Network
- PRBS – Pseudo-Random Bit Sequence
- PSN – Packet Switched Network
- PSTN – Public Switched Telephone Network
- PWE3 – Pseudo-Wire Edge-to-Edge Emulation
- PW – Pseudo Wire
- QoS – Quality of Service
- QRBS – Quasi-Random Bit Sequence
- RAM – Random Access Memory
- Rcv – Receive
- RXP – Receive Packet direction “from Ethernet Port to TDM Port”
- SAT – abbreviation for SAToP
- SAToP – Structure-Agnostic TDM over Packet
- SDH – Synchronous Digital Hierarchy
- SDRAM – Synchronous Dynamic RAM
- SN – Sequence Number
- SONET –Synchronous Optical Network
- SS7 – Signaling System 7
- T1 – commonly used term for DS1
- T1-ESF – T1 Extended Super-frame
- T1-SF – T1 Super-frame
- T1/E1 – T1 or E1
- TCXO – Temperature Compensated Crystal Oscillator
- TDM – Time Division Multiplexing
- TDMoIP – TDM over IP
- TDMoP – TDM over Packet
- Timeslot – 64 Kb/s channel within an E1 or T1
- TS – Timeslot
- TXP – Transmit Packet direction “from TDM Port to Ethernet Port”
- UDP – User Datagram Protocol
- VCCV – Virtual Circuit Connectivity Verification
- VoIP – Voice over IP
- WAN – Wide Area Network
- Xmt - Transmit

3 APPLICABLE STANDARDS

Table 3-1. Applicable Standards

SPECIFICATION	SPECIFICATION TITLE
ANSI	
T1.102	<i>Digital Hierarchy—Electrical Interfaces</i> , 1993
T1.107	<i>Digital Hierarchy—Formats Specification</i> , 1995
T1.403	<i>Network and Customer Installation Interfaces—DS1 Electrical Interface</i> , 1999
ETSI	
ETS 300 011	<i>ISDN Primary Rate User Network Interface (UNI); Part 1: Layer 1 Spec. V1.2.2</i> (2000-05)
IEEE	
IEEE 802.1Q	<i>Virtual Bridged Local Area Networks</i> (2003)
IEEE 802.3	<i>Carrier Sense Multiple Access with Collision Detection Access Method and Physical Layer Spec.</i> (2005)
IEEE 1149.1	<i>Standard Test Access Port and Boundary-Scan Architecture</i> , 1990
IETF	
RFC 4553	<i>Structure-Agnostic Time Division Multiplexing (TDM) over Packet (SAToP)</i> (06/2006)
RFC 4618	<i>Encapsulation Methods for Transport of PPP/High-Level Data Link Control (HDLC) over MPLS Networks</i> (09/2006)
RFC 5086	<i>Structure-Aware Time Division Multiplexed (TDM) Circuit Emulation Service over Packet Switched Network (CESoPSN)</i> (12/2007)
RFC 5087	<i>Time Division Multiplexing over IP (TDMoIP)</i> (12/2007)
ITU-T	
G.704	<i>Synchronous Frame Structures at 1544, 6312, 2048, 8448 and 44736 kbit/s Levels</i> (10/1998)
G.732	<i>Characteristics of Primary PCM Multiplex Equipment Operating at 2048Kbit/s</i> (11/1988)
G.736	<i>Characteristics of Synchronous Digital Multiplex Equipment Operating at 2048Kbit/s</i> (03/1993)
G.823	<i>The Control of Jitter and Wander in Digital Networks Based on 2048kbps Hierarchy</i> (03/2000)
G.824	<i>The Control of Jitter and Wander in Digital Networks Based on 1544kbps Hierarchy</i> (03/2000)
G.8261/Y.1361	<i>Timing and Synchronization Aspects in Packet Networks</i> (05/2006)
G.8261/Y.1361	<i>Timing and Synchronization Aspects in Packet Networks</i> (12/2006). Corrigendum 1.
I.431	<i>Primary Rate User-Network Interface - Layer 1 Specification</i> (03/1993)
O.151	<i>Error Performance Measuring Equipment Operating at the Primary Rate and Above</i> (1992)
Y.1413	<i>TDM-MPLS Network Interworking – User Plane Interworking</i> (03/2004)
Y.1413	<i>TDM-MPLS Network Interworking – User Plane Interworking</i> (10/2005). Corrigendum 1.
Y.1414	<i>Voice Services—MPLS Network Interworking</i> (07/2004)
Y.1453	<i>TDM-IP Interworking – User Plane Networking</i> (03/2006)
MEF	
MEF 8	<i>Implementation Agree. for Emulation of PDH Circuits over Metro Ethernet Networks</i> (10/2004)
MFA	
MFA 8.0.0	<i>Emulation of TDM Circuits over MPLS Using Raw Encapsulation – Implement. Agree.</i> (11/2004)

Note: Only those sections of these standards that are affected by the DS34S132 functions are considered applicable. For example, several of the standards specify T1/E1 Framing/LIU functions (e.g. pulse shape) that are not included in the DS34S132 but also specify jitter/wander functions that are applicable.

4 HIGH LEVEL DESCRIPTION

To implement a PW (tunnel) across a PSN requires a PW termination point at each end of the PW (tunnel). Each terminating point provides the PW encapsulation functions that are required to enter the PSN (for one direction of data) and the PW de-encapsulation functions to restore the data to its original (non-PW) format (for the opposite direction). The two data directions at each termination point can be described as the “transmit PW packet direction” (TXP) and the “receive PW packet direction” (RXP).

The DS34S132 TDMoP device implements the complete, bi-directional PW termination point encapsulation functions for TDMoP and HDLC PWs. The DS34S132 is a high density solution that can terminate up to 256 PWs that are associated with up to 32 T1/E1 data streams and aggregate that traffic for transmission over a single 100/1000 Mb/s Ethernet data stream. The DS34S132 can encap/decap TDMoP and HDLC PWs into the following PSN protocols: L2TPv3/IPv4, L2TPv3/IPv6, UDP/IPv4, UDP/IPv6, Metro Ethernet (MEF-8) and MPLS (MFA-8).

For TDMoP PWs the DS34S132 supports the SAToP and CESoPSN payload formats. SAToP is used for Unstructured TDM transport, where an entire T1/E1 including the framing pattern (if it exists) is transferred transparently as a series of unformatted bytes of data in the PW payload without regard to any bit, byte and/or frame alignment that may exist in the TDM data stream. The DS34S132 can support Unstructured T1, E1 or slower TDM data streams (any bit rate less than or equal to 2.048 Mb/s).

CESoPSN is used for Structured TDM transport where the PW packet payload is synchronized to the T1/E1 framing. With CESoPSN the T1/E1 framing pattern is commonly not passed across the PW (removed) because the structured PW format enables the framing information to be conveyed through the PW mechanisms. The opposite end generates the T1/E1 framing pattern from the PWs payload structure. This payload format can be used when the TDM service (e.g. voice) requires the ability to interpret, and/or terminate some functional aspects of the T1/E1 signal (e.g. identify DS0s within the T1/E1). PWs with the Structured payload format can support Nx64 Kb/s, fractional T1/E1 (T1: N = 1 – 24; E1: N = 1 – 32). In some applications, a T1/E1 can be divided into multiple Nx64 blocks (M x N x 64; M = the number of fractional blocks) and the PSN can be used as a “distributed cross-connect” to implement a point to multi-point topology forwarding some Nx64 blocks to one end point and other Nx64 blocks to other end points (T1: M = 1 – 24; E1: M = 1 – 32; e.g. for E1: 32 x 1 x 64).

The CESoPSN Structured format can also convey CAS Signaling across a PW through the use of a sub-channel within the CESoPSN PW packets. The DS34S132 enables the CAS Signaling to be transparently passed, monitored by an external CPU, and/or terminated by an external CPU, all on a per Timeslot and per direction basis.

The DS34S132 allows each TDM Port to independently support asynchronous or synchronous TDM data streams. Each TDM Port has a Clock Recovery Engine to regenerate the timing from a TDMoP PW packet data stream. For applications that do not require clock recovery the DS34S132 also provides several external clocking options.

The Clock Recovery Engines support Differential Clock Recovery (DCR) and Adaptive Clock Recovery (ACR). DCR can be used when a common clock is available at both ends of the PW (e.g. BITS clock for the public network or GPS for the mobile cellular network) and requires that the PW use RTP Timestamps to convey the TDM timing information. Adaptive Clock Recovery does not use Timestamps but instead regenerates the timing based on the TDMoP PW packet transmission rate. The DS34S132 high performance clock recovery circuits enable the use of PWs in the public network by achieving the stringent jitter and wander performance requirements of ITU-T G.823/824/8261, even for networks that impose large packet delay variation (PDV) and packet loss. For far end clock recovery, the DS34S132 can generate two Timestamp formats - Absolute and Differential Timestamps.

PWs can be used to transport HDLC packet data. The DS34S132 can forward HDLC encapsulated data transparently using a TDMoP PW (as described above; idle HDLC Flags are forwarded with the data) or by first extracting the data from the HDLC coding and then only forwarding the non-idle data in an HDLC PW. The HDLC PW is useful for HDLC data streams where a significant portion of the data stream is filled with HDLC Idle Flags. For example, if a 64 Kb/s TDM Timeslot is used to carry 4 Kb/s of HDLC data then it may be more bandwidth efficient to extract the payload data from the HDLC encoding and forward the data over an HDLC PW. The DS34S132 incorporates 256 HDLC Engines so that any PW can be assigned as a TDMoP PW or an HDLC PW.

PW Termination points often must also terminate OAM and Signaling packet data streams. To support this need the DS34S132 enables an external CPU to terminate several OAM and Signaling types including: PW In-band VCCV OAM, PW UDP-specific (Out-band VCCV) OAM, MEF OAM, Ethernet Broadcast frames, ARP, IPv6 NDP and includes a user specified CPU-destination Ethernet Type. The DS34S132 can also be programmed to forward packets to the CPU that match specialized conditions for debug or other purposes (e.g. wrong IP DA).

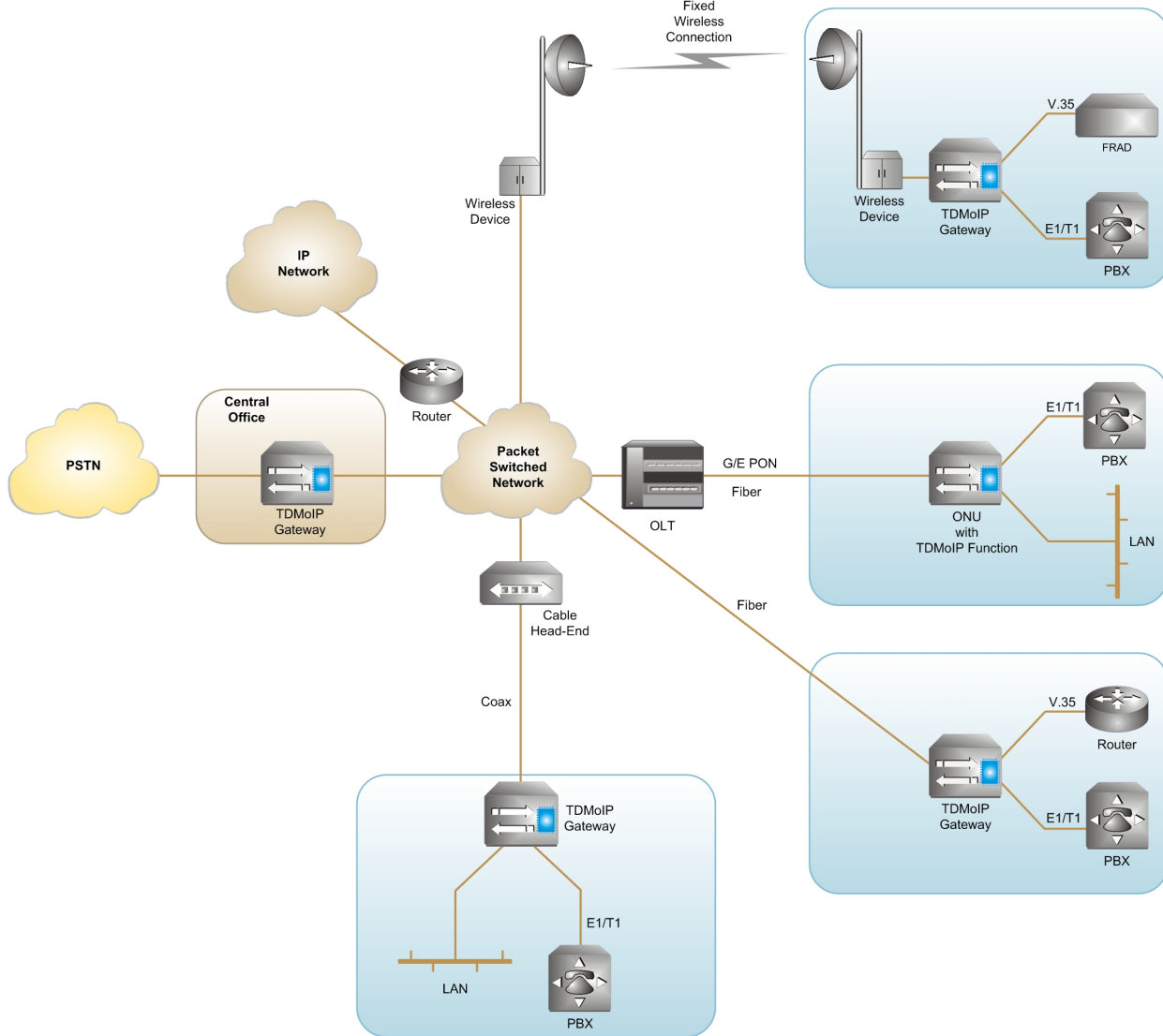
The DS34S132 uses an external DDR SDRAM device to buffer data. The large memory supplies sufficient buffer space to support a 256 ms PDV for each of the 256 PW/Bundles and to enable packet re-ordering for packets that are received out of order (the PSN may mis-order the packets). This large memory is also used to buffer the HDLC data streams and the CPU terminated OAM and Signaling packets.

TDMoP provides the perfect transition technology for next generation packet networks enabling the continued use of the vast Legacy network and at the same time supplementing new packet based technologies.

5 APPLICATION EXAMPLES

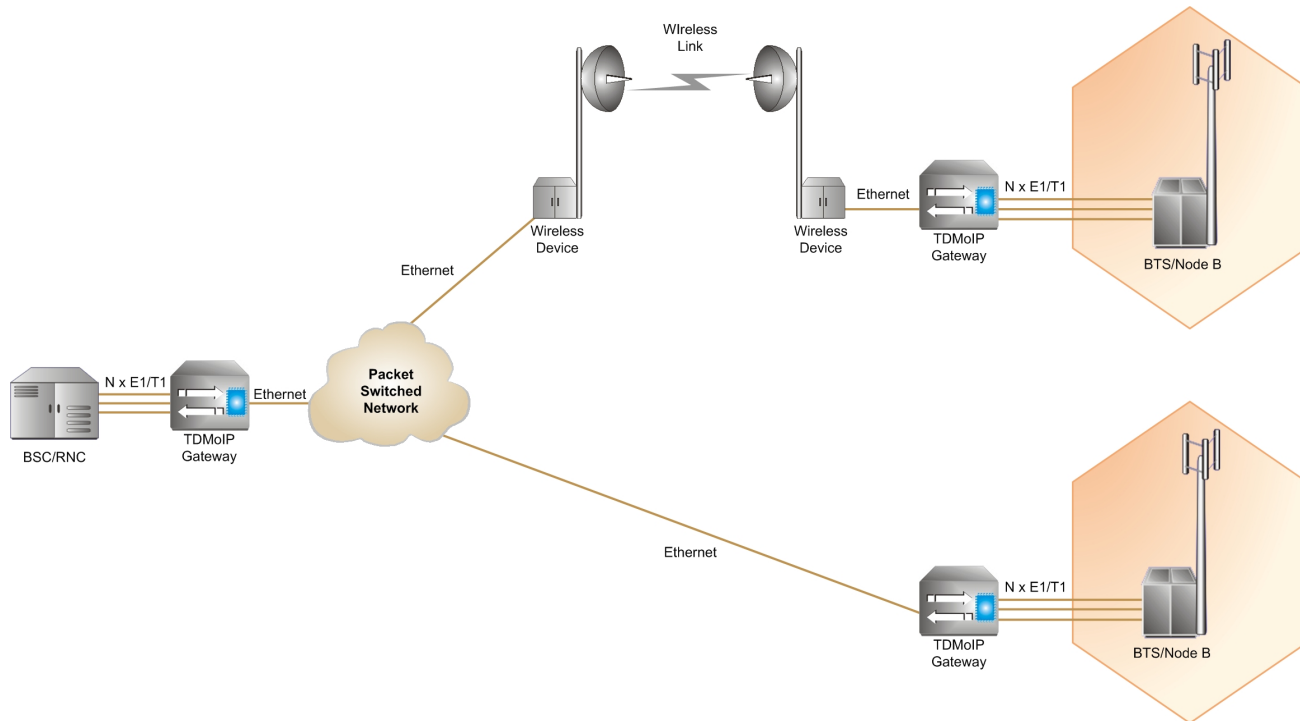
In [Figure 5-1](#), TDMoP devices are used in gateway nodes to transport TDM services through a metropolitan PSN. The Maxim TDMoP family of devices offers a range of density solutions so that lower density solutions like the DS34T101 can be used in Service Provider Edge applications, to support a small number of T1/E1 lines, and higher density solutions like the DS34S132 can be used in Central Office applications, to terminate several Service Provider Edge nodes. PWs can be carried over fiber, wireless, SONET/SDH, G/EPON, coax, etc.

Figure 5-1. TDMoP in a Metropolitan Packet Switched Network



In [Figure 5-2](#), DS34S132 devices are used in TDMoP gateways to enable TDM services to be transported through a Cellular Backhaul PSN.

Figure 5-2. TDMoP in Cellular Backhaul



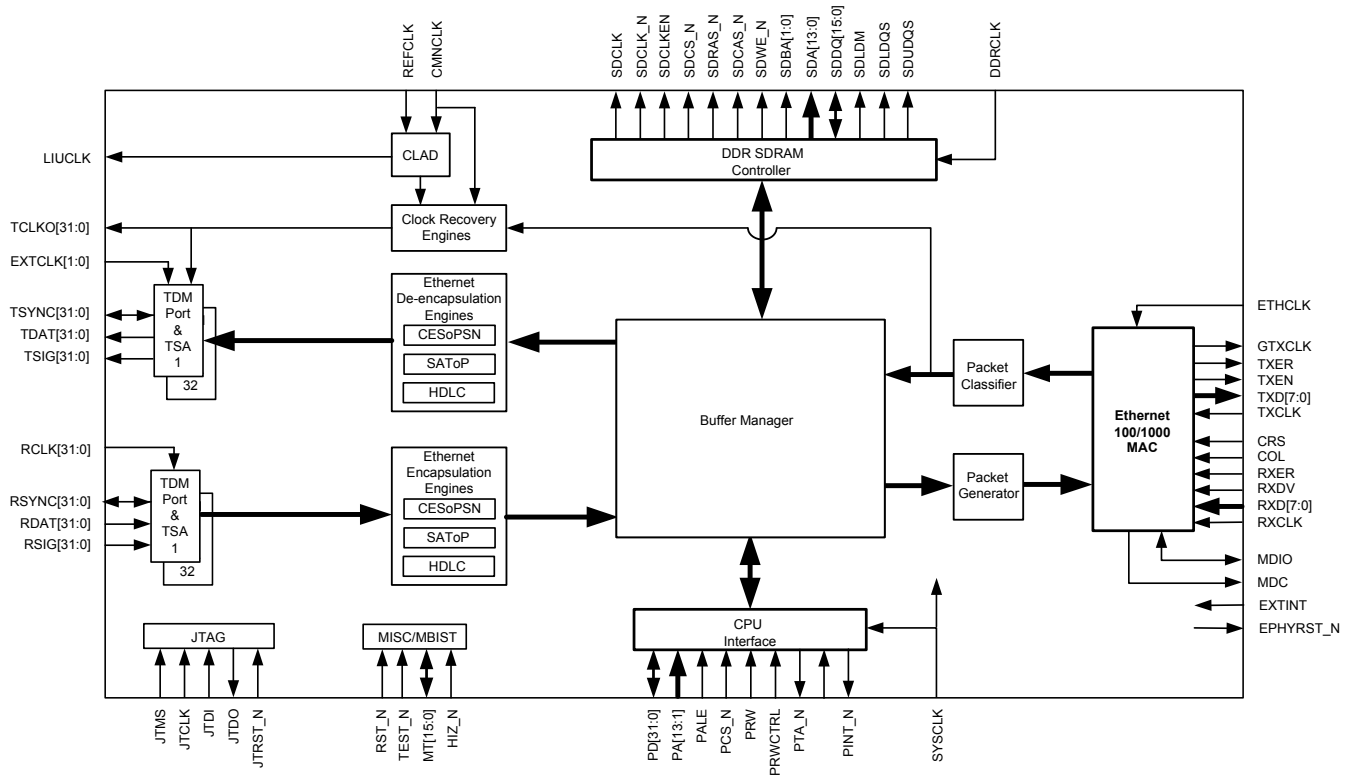
Other Possible Applications

Using a Packet Backplane for Multiservice Concentrators

Communications platforms with all/any of the above-mentioned capabilities can replace obsolete, low bandwidth TDM buses with low cost, high bandwidth Ethernet buses. The DS34S132 provides the interworking functions that are needed to packetize TDM services so that they can be multiplexed together with bursty services for transmission over a unified backplane bus. This enables a cost-effective, future-proof design with full support for both legacy and next-generation services.

6 BLOCK DIAGRAM

Figure 6-1. DS34S132 Functional Block Diagram



7 FEATURES

TDM Port Features

- TDM Ports
 - 32 TDM Ports, each with independently configured Framing Format
 - T1/E1 Structured (with T1/E1 Framing)
 - T1-SF, T1-ESF and E1 CAS Multi-frame formats
 - With and Without CAS Signaling
 - CAS embedded in data bus using RDAT/TDAT pins
 - Parallel CAS Interface using RSIG/TSIG pins
 - Unstructured (without Framing) - T1, E1 and slower TDM line rates (any line rate \leq 2.048 Mb/s)
- TDM Port Timing References
 - TDM Port Clocks
 - Asynchronous or Synchronous TDM Port Timing
 - Independent Receive and Transmit Clocks
 - Transmit TDM Port Timing
 - RXP packet stream Clock Recovery
 - One Clock Recovery Engine per TDM Port
 - Global Clock Recovery Engine
 - EXTCLK0 or EXTCLK1 External clock reference
 - External RCLK signal (Loop timed)
 - Receive TDM Port Timing
 - External RCLK signal
 - Internally generated Transmit timing (for synchronous systems)
 - TDM Multi-frame Synchronization for CAS Signaling
 - Independent Receive and Transmit Multi-frame Synchronization for each TDM Port
 - E1, T1-SF and T1-ESF Multi-frame Synchronization
 - External input or internally generated Multi-frame synchronization
- TDM Port Clock Recovery Engines
 - Adaptive Clock Recovery or
 - Differential Clock Recovery
 - Common Clock (CMNCLK) frequency = 1MHz to 25MHz (in 8kHz increments)
 - RTP Differential Timestamp
 - Generation of Absolute Timestamps and Differential Timestamps
 - External 5.0 MHz – 155.52 MHz clock input (REFCLK) for internal Clock Recovery synthesizer
 - Fast Frequency Acquisition and Highly Accurate Phase Tracking
 - Recovered Clock Jitter and Wander per ITU-T G.823/G.824/G.8261 with Stratum 3 clock reference
 - High resilience to Packet Loss and Robust to Sudden Significant Constant Delay Changes
 - Automatic transition to hold-over during alarm/event impairments
- TDM Port Timeslot Assignment (TSA), CAS and Conditioning
 - Nx64 Kb/s – any combination of T1/E1 Timeslots from one TDM Port can be assigned to a PW/Bundle
 - T1/E1 CAS Signaling (Channel Associated Signaling)
 - Transparent CAS (forwarded from TDM to Ethernet Port and from Ethernet to TDM Port)
 - Per Timeslot CPU Controlled CAS (CPU inserts CAS; in TXP and/or RXP directions)
 - CAS Status and Change of Status for CPU Monitoring (in RXP and TXP directions)
 - Data Conditioning – can force any 8-bit pattern on any number of Timeslots (in RXP and TXP directions)

Ethernet Port Features

- Ethernet MAC Interface
 - 100/1000 Mb/s Operation using MII/GMII Interface
 - 2 programmable receive Ethernet Destination Addresses
 - Mixed Ethernet II (DIX) and IEEE 802.2 LLC/SNAP formats
 - Mixed data streams with 0, 1, or 2 VLAN Tags
 - Programmable VLAN TPID
 - Ethernet Frame Length 64 bytes to 2000 bytes

PW/Bundle Features

- RXP PW/Bundle Header
 - Up to 256 programmed PW/Bundles (32 per TDM Port)
 - PW Header Types
 - L2TPv3 / IPv6
 - L2TPv3 / IPv4
 - UDP / IPv4
 - UDP / IPv6
 - MEF (MEF-8)
 - MPLS (MFA-8)
 - Mixed MPLS data streams with 0, 1 or 2 MPLS Outer Labels
 - Mixed L2TPv3 data streams with 0, 1, or 2 L2TPv3 Cookies
 - Flexible UDP settings
 - 16-bit (standard) or 32-bit (extended) UDP PW-ID bit width
 - 16-bit UDP PW-ID selectable to be verified against UDP Source or Destination Port
 - Optional 16-bit PW-ID Mask
 - Ignore UDP Payload Protocol or verify against 2 programmable UDP Payload Protocol Values
 - Optional PW Control Word
 - Optional “In-band VCCV” Monitoring
 - Programmable 16-bit In-band VCCV value with programmable 16-bit In-band VCCV mask
 - Optional RTP Header
 - One PW/Bundle per TDM Port can be assigned to provide RTP Timestamp for Clock Recovery
 - Sequence Number
 - Selectable between Control Word or RTP Sequence Number
 - Used to initiate conditioning data when packets are missing
 - Optional re-ordering of mis-ordered packets up to the Size of the Jitter Buffer depth
 - Up to 32 UDP-Specific (Out-band VCCV) OAM PW-IDs
 - Debug settings to forward PW/Bundles with special conditions to CPU for analysis (e.g. wrong IP DA)
- TXP PW/Bundle Header
 - Store up to 256 CPU generated PW/Bundle Headers (one per PW/Bundle)
 - Maximum 122 byte header with any CPU-specified content (Layer 2/3/4 content)
 - Auto generate and insert Length and FCS functions for IP and UDP Headers
 - Optional RTP Timestamp Insertion
 - Any number of TXP PW/Bundles can be assigned to include Timestamp in RTP Header
 - Optional RTP and Control Word Sequence Number Insertion
 - 3 HDLC Sequence Number generation modes
 - Sequence Numbers with “fixed at zero” value
 - Sequence Numbers with incremented counting using “skip zero at Rollover”
 - Sequence Numbers with incremented counting using “include zero at Rollover”
- PW/Bundle Payload Types
 - TDMoP PW/Bundles (non-HDLC) - Constant Bit Rate Services (e.g. PCM voice)
 - Unstructured PW Payload (without framing; SAToP): E1, T1 and slower TDM bit rate (≤ 2.048 Mb/s)
 - Structured PW Payload (with framing; CESoPSN)
 - E1, T1-SF and T1-ESF formats

- Any Nx64 Kb/s bit rate from a single T1 or E1 TDM Port
 - With or without CAS Signaling
- HDLC PW/Bundles (e.g. SS7 Signaling)
 - Unstructured PW Payload: E1, T1 and slower TDM bit rate (≤ 2.048 Mb/s)
 - Structured PW Payload: Any Nx64 Kb/s bit rate from a single T1 or E1 TDM Port (for 8-bit HDLC)
- CES/SAT Processing
 - 256 CES/SAT Engines (one per PW/Bundle)
 - Per PW/Bundle Settings
 - Any Payload Size (up to maximum 2000 byte Ethernet Packet length)
 - Optional “zero” payload size for PW/Bundles that are only used for Clock Recovery
 - RXP Jitter Buffer (to compensate for PDV and for packet re-ordering; up to 500 ms)
 - Programmable “Begin Play-out Watermark” (for PDVT)
 - TXP high or low priority queue scheduling
- HDLC Processing
 - 256 HDLC Engines (one per PW/Bundle)
 - Configurable Transmit TDM Port minimum number of Intra-frame Flags (1 to 8)
 - Per Engine Settings
 - 2-bit, 7-bit or 8-bit HDLC coding
 - 16-bit, 32-bit or “no” Trailing HDLC FCS
 - Intra-frame Flag Value (0xFF or 0x7E)
 - HDLC Transmission Bit Order using MSB first or LSB first

CPU Interface Features

- CPU Packet Interface (for CPU-based OAM and Signaling)
 - Stores up to 512 Transmit and 512 Receive Packets that can be 64 byte to 2000 byte in length
 - RXP direction
 - Provides detected packet type with each received RXP CPU packet
 - In-band VCCV OAM
 - UDP-specific (Out-band VCCV) OAM
 - MEF OAM Ethernet Type
 - Configured “CPU Ethernet Type”
 - ARP
 - Broadcast Ethernet DA
 - Several Packet Header Conditions (e.g. NDP/IPv6 & unknown IP DA)
 - Provides Local Timestamp indicating the time the packet was received (in 1 us or 100 us units)
 - TXP direction
 - Any CPU generated Header and Payload (any Layer 2/3/4 content)
 - Support for IP FCS and UDP FCS Generation
 - Optionally inserts TXP OAM Timestamps (in 1 us or 100 us units)
- DS34S132 Control Interface
 - MPC8xx or MPC83xx synchronous interface using a 50 to 80 MHz clock rate (the MPC8xx and MPC83xx are processor product families of Freescale Semiconductor, Inc.)
 - Selectable 16-bit or 32-bit data bus
 - DS34S132 device Control & Sense Registers
 - Mask-able Interrupt Hierarchy for Change of Status, Alarms and Events
 - Ethernet Port RMON Statistics

Miscellaneous

- Loopbacks
 - PW/Bundle Loopback (payload from RXP PW packets are transmitted in TXP PW packets)
 - TDM Port Line Loopback (all data from Receive TDM Port sent to Transmit TDM Port using RCLK)

- TDM Port Timeslot Loopback (from Receive to Transmit TDM Port Timeslot using RCLK)
- TDM Port and/or Ethernet Port BERT Testing
 - Half Channel (one-way) or Full Channel (round-trip) Testing
 - Flexible PRBS, QRBS or Fixed Pattern Testing
- 16-bit DDR SDRAM Interface that does not require any glue-logic
- IEEE 1149.1 JTAG support
- MBIST (memory built-in self test)
- 1.8V Core, 2.5V DDR SDRAM and 3.3V I/O that are 5V tolerant
- 27 x 27 mm, 676-pin BGA package (1mm pitch)

8 PIN DESCRIPTIONS

8.1 Short Pin Descriptions

Table 8-1. DS34S132 Short Pin Descriptions

Name	Type	Function
TDM Port n = 0 through 31 Ports		
TCLK _n	Oz	Transmit TDM Clock Output
TSYNC _n	IO	Transmit Frame (Frame or Multi-frame Sync Pulse)
TDAT _n	Oz	Transmit NRZ Data
TSIGN	Oz	Transmit Signaling
RCLK _n	I	Receive Clock Input
RSYNC _n	IO	Receive Frame (Frame or Multi-frame Sync Pulse)
RDAT _n	I	Receive NRZ Data
RSIGN	I	Receive Signaling
100/1000 Mbps Ethernet MAC Interface (GMII/MII)		
TXCLK	Ipu	MII Transmit clock (25 MHz)
GTXCLK	Oz	GMII Transmit clock (125 MHz)
TXD[7:0]	Oz	GMII/MII Transmit data
TXEN	Oz	GMII/MII Transmit data enable
TXER	Oz	GMII/MII Transmit packet frame invalid
RXCLK	Ipu	GMII/MII Receive clock (25 MHz or 125 MHz)
RXD[7:0]	I	GMII/MII Receive data
RXDV	I	GMII/MII Receive data valid
RXER	I	GMII/MII Receive error
COL	I	MII Collision Detection (not used)
CRS	I	Carrier Sense Detection (not used)
MDC	Oz	Management Data Clock
MDIO	IO	Management Data Input/Output
CPU Interface		
PD[31:0]	IO	Data [31:0]
PA[13:1]	I	Address [13:1]
PALE	I	Address Latch Enable
PCS_N	I	Chip Select (active low)
PRW	I	Read/Write
PRWCTRL	I	Read/Write Control
PTA_N	Oz	Transfer Acknowledge (active low)
PWIDTH	I	Processor Bus Width
PINT_N	Oz	Interrupt Out (active low)
External Memory Interface – DDR SDRAM		
SDCLK, SDCLK_N	Oz	SDRAM Clock
SDCLKEN	Oz	Clock Enable
SDCS_N	Oz	Chip Select (active low)
SDRAS_N	Oz	RAS (active low)
SDCAS_N	Oz	CAS (active low)
SDWE_N	Oz	Write Enable (active low)
SDBA[1:0]	Oz	Bank Address Select
SDA[13:0]	Oz	Address
SDDQ[15:0]	IO	Bi-directional Data Bus
SDLDM	Oz	Lower Byte Data Mask
SDUDM	Oz	Upper Byte Data Mask

Name	Type*	Function
SDLDQS	Oz	Lower Byte Data Strobe
SDUDQS	Oz	Upper Byte Data Strobe
Clocks, Resets , JTAG & Miscellaneous		
CMNCLK	I	Optional Differential Clock Recovery Common Clock (8kHz to 25MHz)
EXTCLK[1:0]	I	2 Independent Optional External Clocks for TDM Port Transmit Timing
SYSClk	I	System Clock for CPU Interface (50 MHz to 80MHz)
LIUCLK	Oz	1.544MHz or 2.048MHz
REFCLK	I	Optional Oscillator Reference for Clock Recovery (5 MHz to 155.52 MHz)
DDRCLK	I	DDR SDRAM clock (125MHz)
ETHCLK	I	Optional Clock for GMII operation & OAM Timestamps (25MHz or 125MHz)
EXTINT	I	Ethernet Phy Interrupt (if MDIO/MDC are not used)
EPHYRST_N	Oz	Ethernet Phy Reset signal
RST_N	I	Global Reset
JTCLK	I	JTAG Clock
JTMS	Ipu	JTAG Mode Select
JTDI	Ipu	JTAG Data Input
JTDO	Oz	JTAG Data Output
JTRST_N	Ipu	JTAG Reset (active low)
HIZ_N	I	High impedance test enable (active low)
TEST_N	I	Test enable (active low)
MT[15:0]	IO	Manufacturing Test
SMTI	Ipu	Manufacturing Test Input, Must be tied to VCC33.
SMTO	O	Manufacturing Test Output, Must be left unconnected (floating).
Power Supply Signals		
VDD33	pwr	Core Digital 3.3 Volt Power Supply Input
VDD18	pwr	Core Digital 1.8 Volt Power Supply Input
VSS	pwr	Ground for 3.3V and 1.8V supplies. Connect to Common Supply Ground
AVDD	pwr	SDRAM 1.8 Volt PLL Power (may be connected CVDD)
AVSS	pwr	AVDD Ground (may be connected to CVSS)
CVDD	pwr	CLAD 1.8 Volt Power (may be connected to AVDD)
CVSS	pwr	CVDD Ground (may be connected to AVSS)
VDDP	pwr	SDRAM Digital Core 2.5 Volt Power Supply Input
VDDQ	pwr	SDRAM DQ 2.5 Volt Power Supply Input
VSSQ	pwr	SDRAM Digital Ground for VDDP and VDDQ
VREF	pwr	SDRAM SSTL_2 Reference Voltage (one-half VDDQ)

Note: * n = 0 to 31 (port number), Ipu = input with pullup, Oz = output tri-stateable, IO = Bi-directional input/output

8.2 Detailed Pin Descriptions

Table 8-2. Detailed Pin Descriptions

Pin Name	Type	Pin Description
TDM Port n = 0 through 31 Ports		
TCLKOn	Oz	Transmit Clock Output. TCLKOn is derived from the clock recovery engine or from RCLKn when in loop-timed mode or from the EXTCLK signal.
TSYNCn	IO	Transmit Sync. TSYNCn may be a frame or multi-frame input or output signal. Each frame is a 125 us time period. The frame count for each multi-frame type is: T1-SF = 12; T1-ESF = 24; E1 = 16. If configured as an input, it is sampled by TCLKOn. If configured as an output, it is output with respect to TCLKOn.
TDATn	Oz	Transmit Data Output. TDATn is the TDM datastream recovered from the PSN, output with respect to TCLKOn.
TSIGN	Oz	Transmit Signaling. TSIGN is the transmit signaling recovered from the PSN, output with respect to TCLKOn. The CAS values are updated once every TSYNC period.
RCLKn	I	Receive Clock. RCLKn is input clock typically derived from a T1/E1 framer or LIU.
RSYNCn	I	Receive Sync. RSYNCn indicates the frame or multi-frame boundary for the T1/E1 datastream, typically derived from a T1/E1 framer or LIU and sampled by RCLKn. Each frame is a 125 us period. The frame count for each multi-frame type is: T1-SF = 12; T1-ESF = 24; E1 = 16.
RDATn	I	Receive Data. RDATn is the receive TDM datastream typically derived from a T1/E1 framer or LIU, sampled by RCLKn.
RSIGN	I	Receive Signaling. RSIGN is the receive signaling typically derived from a T1/E1 framer, sampled by RCLKn. The CAS values are updated once every RSYNC period.
100/1000 Mbps Ethernet MAC Interface (GMII/MII)		
TXCLK	Ipu	Transmit Clock (MII). Timing reference for TXEN and TXD[0:3]. The TXCLK frequency is 25 MHz for 100 Mbit/s operation.
GTXCLK	Oz	GMII Transmit Clock Output. 125MHz clock output available for GMII operation. This clock is synchronous to ETHCLK input.
TXD[0:7]	Oz	Transmit Data 0 through 7(GMII Mode – TXD[0:7]). TXD[0:7] is presented synchronously with the rising edge of TXCLK. TXD[0] is the least significant bit of the data. When TXEN is low the data on TXD should be ignored. Transmit Data 0 through 3(MII Mode – TXD[0:3]). Four bits of data TXD[0:3] presented synchronously with the rising edge of TXCLK. When MII mode is selected, TXD[4:7] pins are not used.
TXEN	Oz	Transmit Enable (GMII). When this signal is asserted, the data on TXD[0:7] is valid; synchronous with GTXCLK. Transmit Enable (MII). In MII mode, this pin is asserted high when data TXD[0:3] is being provided by the device. This signal is synchronous with the rising edge TXCLK. It is asserted with the first bit of the preamble. Synchronous with TXCLK.
TXER	Oz	Transmit Error (GMII, MII). When this signal is asserted, the PHY will respond by sending one or more code groups in error.
RXCLK	Ipu	Receive Clock (GMII). 125 MHz clock. This clock is used to sample the RXD[0:7] data. Receive Clock (MII). Timing reference for RXDV, RXER and RXD[0:3], which are clocked on the rising edge. RXCLK frequency is 25 MHz for 100 Mbit/s operation.

Pin Name	Type	Pin Description
RXD[7:0]	I	<p>Receive Data 0 through 7(GMII Mode – RXD[0:7]). Eight bits of received data, sampled synchronously with the rising edge of RXCLK. For every clock cycle, the PHY transfers 8 bits to the device. RXD[0] is the least significant bit of the data. Data is not considered valid when RXDV is low.</p> <p>Receive Data 0 through 3(MII Mode – RXD[0:3]). Four bits of received data, sampled synchronously with RXCLK. Accepted when CRS is asserted. When MII mode is selected, RXD[4:7] pins are not used.</p>
RXDV	I	<p>Receive Data Valid (GMII). This active high signal, synchronous to RXCLK, indicates valid data from the PHY. In GMII mode the data RXD[0:7] is ignored if RXDV is not asserted high.</p> <p>Receive Data Valid (MII). This active high signal, synchronous to RXCLK, indicates valid data from the PHY. In MII mode the data RXD[0:3] is ignored if RXDV is not asserted high.</p>
RXER	I	<p>Receive Error (GMII). This signal indicates a receive error or a carrier extension in the GMII Mode.</p> <p>Receive Error (MII). Asserted by the PHY for one or more RXCLK periods indicating that an error has occurred. Active high indicates receive packet is invalid.</p> <p>MII and GMII modes: This is synchronous with RXCLK.</p>
COL	I	Collision Detect (MII). Asserted by the Ethernet PHY to indicate that a collision is occurring. This signal is only valid in half duplex mode, and is ignored in full duplex mode.
CRS	I	Receive Carrier Sense. This signal is asserted by the PHY when either transmit or receive medium is active. This signal is not synchronous to any of the clocks.
MDC	Oz	Management Data Clock. A divided down SYSCLK that clocks management data to and from the PHY.
MDIO	IO	Management Data IO. Data path for control information between the device and the PHY. Pull to logic high externally through a 1.5K ohm resistor. The MDC and MDIO pins are used to write or read up to 32 Control and Status Registers in PHY Controllers. This port can also be used to initiate Auto-Negotiation for the PHY.
CPU Interface		
PD[31:0]	IO	<p>32-bit Processor Data Bus. PD[31] is the MSB which should be mapped to D[0] of a MPC8xxx processor.</p> <p>16-bit Processor Data Bus. PD[15] is the MSB which should be mapped to D[0] of a MPC8xxx processor. PD[31:16] is not used and should be tied low.</p> <p>32-bit & 16-bit Processor Data Bus. Input signals on this bus are captured by the rising edge of SYSCLK. Output signals are updated on the rising edge of SYSCLK.</p>
PA[13:2]	I	Processor Address Bus. The signals on this bus are captured by the rising edge of SYSCLK.
PA[1]	I	<p>32-bit Processor Address Bus Bit 1. PA[1] is not used and should be tied low.</p> <p>32-bit Processor Address Bus Bit 1. When PA[1] = 0, PD[15:0] carries the upper 16 bits of the 32-bit word. When PA[1] = 1, PD[15:0] carries the lower 16 bits of the 32-bit word.</p>
PALE	I	Processor Address Latch. PALE latches PA[13:1] on its falling edge. In non-muxed mode, tie high.
PCS_N	I	Processor Chip Select. Processor chip select active low. Synchronous to SYSCLK.
PRW	I	Processor Read/Write. The behavior of this signal is described by PRWCTRL. This signal is synchronous to SYSCLK.

Pin Name	Type	Pin Description
PRWCTRL	I	Processor Read/Write Control. 0 = PRW is high for a write, low for a read (PQ II Pro mode) 1 = PRW is low for a write, high for a read (PQ I mode)
PTA_N	Oz	Processor Transfer Acknowledge. This signal indicates to the processor on a read that data is valid on the data bus. On a write, it indicates that the DS34S132 is ready for a new transaction. This signal is synchronous to SYSClk since the PowerQuicc I requires it. This signal requires an external pull-up. On the PowerQuicc I, the PTA_N is used as a data valid signal and therefore must be coincident with the data on read accesses (i.e. it may not be early.)
PWIDTH	I	Processor Bus Width 0 = 16-bit mode 1 = 32-bit mode
PINT_N	Oz	Processor Interrupt. When the bit configurable Interrupt Inactive Mode is '0', this pin is active low, asynchronous to SYSClk and is high impedance when not active. When the bit configurable Interrupt Inactive Mode is '1', this pin is active low, asynchronous to SYSClk and drives high when no interrupts are active.
External Memory Interface – DDR SDRAM		
SDCLK, SDCLK_N	Oz	SDRAM Clock. SDCLK and SDCLK_N are differential clock outputs. (Both pins are referenced collectively as SDCLK.) All address and control input signals are sampled on the positive edge of SDCLK and negative edge of SDCLK. Output (write) data is referenced to the rising edge and falling edge of SDCLK.
SDCLKEN	Oz	SDRAM Clock Enable. Active High. SDCLKEN must be active throughout DDR SDRAM READ and WRITE accesses.
SDCS_N	Oz	SDRAM Chip Select. All commands are masked when SDCS_N is registered high. SDCS_N provides for external bank selection on systems with multiple banks. SDCS_N is considered part of the command code.
SDRAS_N	Oz	SDRAM Row Address Strobe. Active low output, used to latch the row address on rising edge of SDCLK. It is used with commands for Bank Activate, Precharge, and Mode Register Write.
SDCAS_N	Oz	SDRAM Column Address Strobe. Active low output, used to latch the column address on the rising edge of SDCLK. It is used with commands for Bank Activate, Precharge, and Mode Register Write.
SDWE_N	Oz	SDRAM Write Enable. This active low output enables write operation and auto precharge.
SDBA[1:0]	Oz	SDRAM Bank Select. These 2 bits select 1 of 4 banks for the read/write/precharge operations.
SDA[13:0]	Oz	SDRAM Address. The 14 pins of the SDRAM address bus output the row address first, followed by the column address. The row address is determined by SDA[0] to SDA[13] at the rising edge of clock. Column address is determined by SDA[0]-SDA[9] at the rising edge of the clock. SDA[10] is used as an auto-precharge signal.
SDDQ[15:0]	IO	SDRAM Data Bus. The 16 pins of the SDRAM data bus are inputs for read operations and outputs for write operations. At all other times, these pins are high-impedance.
SDLDM	Oz	SDRAM Lower Data Mask. SDLDM is an active high output mask signal for write data. SDLDM is updated on both edges of SDLDQS. SD_LDM corresponds to data on SDATA7-SDATA0.
SDUDM	Oz	SDRAM Upper Data Mask. SDUDM is an active high output mask signal for write data. SDUDM is updated on both edges of SDUDQS. SDUDM corresponds to data on SDATA15-SDATA8.
SDLDQS	Oz	SDRAM Lower Data Strobe. Output with write data, input with read data. SDLDQS corresponds to data on SDATA7-SDATA0.
SDUDQS	Oz	SDRAM Upper Data Strobe. Output with write data, input with read data. SDUDQS corresponds to data on SDATA15-SDATA8.

Pin Name	Type	Pin Description
Clocks, Resets , JTAG & Miscellaneous		
CMNCLK	I	Common Clock. This clock is used for Differential Clock Recovery. Common clock has to be a multiple of 8 kHz and in the range of 8 kHz to 25 MHz. The frequency input should not be too close to an integer multiple of the service clock frequency. Based on these criteria, the following frequencies are suggested: <u>SONET/SDH systems:</u> 19.44 MHz <u>ATM systems:</u> 9.72 MHz or 19.44 MHz <u>GPS systems:</u> 8.184 MHz <u>Synchronous Ethernet systems:</u> 25 MHz CMNCLK may also be used in lieu of REFCLK if the CMNCLK frequency matches one of the frequencies used for REFCLK and if CMNCLK is a high quality clock (Stratum 3). When CMNCLK is not used tie to ground or VDD(3.3V).
EXTCLK[1:0]	I	External Clock. This clock is used as an E1 or T1 Station Clock. In this mode, is used for TDATn. When this clock is not used tie to ground or VDD(3.3V).
SYSCLK	I	System Clock. This clock shall be in the range of 50 – 85 MHz and also synchronous with the CPU's bus clock.
LIUCLK	O	LIU Clock. This clock is generated by the CLAD based on either REFCLK or CMNCLK and can be selected to be 1.544 MHz or 2.048 MHz. By default, this clock drives low.
REFCLK	I	Reference Clock. This clock must be one of the following frequencies: 5 MHz, 5.12 MHz, 10 MHz, 10.24 MHz, 12.8 MHz, 13 MHz, 19.44 MHz, 20 MHz, 25 MHz, 30.72 MHz, 38.88 MHz, 77.76 MHz, or 155.52 MHz. This input shall be a stratum 3 quality or better. This clock is selectable by the CLAD to derive the synthesis clock for the clock recovery engine. CMNCLK can be used in lieu of REFCLK.
ETHCLK	I	Ethernet Clock. This clock is used as the source for the GTXCLK in GMII mode and is used as a constant reference for several internal clocks. This signal must always be provided with 125MHz clock +/- 100ppm. It may use the same oscillator as DDRCLK.
DDRCLK	I	DDR Clock. This clock is used as the source for SD0CLK and SDCLK. The clock frequency should be 125 MHz. It may use the same oscillator as ETHCLK.
RST_N	I	Reset. An active low signal on this pin resets the internal registers and logic. While this pin is held low, the microprocessor interface is kept in a high-impedance state. This pin should remain low until power is stable and then set high for normal operation.
JTCLK	I	JTAG Clock. This signal is used to shift data into JTDI on the rising edge and out of JTDO on the falling edge.
JTMS	Ipu	JTAG Mode Select. This pin is sampled on the rising edge of JTCLK and is used to place the test access port into the various defined IEEE 1149.1 states. This pin has a 10k pull up resistor.
JTDI	Ipu	JTAG Data In. Test instructions and data are clocked into this pin on the rising edge of JTCLK. This pin has a 10k pull up resistor.
JTDO	Oz	JTAG Data Out. Test instructions and data are clocked out of this pin on the falling edge of JTCLK. If not used, this pin should be left unconnected.
JTRST_N	Ipu	JTAG Reset. JTRST is used to asynchronously reset the test access port controller. After power up, a rising edge on JTRST will reset the test port and cause the device I/O to enter the JTAG DEVICE ID mode. Pulling JTRST low restores normal device operation. JTRST is pulled HIGH internally via a 10k resistor operation. If boundary scan is not used, this pin should be held low.
TEST_N	I	Test Enable. (active low)
HIZ_N	I	High Impedance test enable. This signal puts all digital output and bi-directional pins in the high impedance state when it is low and JTRST is low. For normal operation tie high. This is an asynchronous input.
EXTINT	I	External PHY Interrupt. PHY Interrupt to MAC, if MDIO and MDC are not used.
MT[15:0]	IO	Manufacturing Test. For normal operation leave these pins unconnected.
SMTI	Ipu	Manufacturing Test Input, Must be tied to VCC33.